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February 2008

74LVT373, 74LVTH373 Low Voltage Octal Transparent Latch with 3-STATE Outputs

Features

- Input and output interface capability to systems at 5V V_{CC}
- Bushold data inputs eliminate the need for external pull-up resistors to hold unused inputs (74LVTH373), also available without bushold feature (74LVT373)
- Live insertion/extraction permitted
- Power Up/Down high impedance provides glitch-free bus loading
- Outputs source/sink -32 mA/+64 mA
- Functionally compatible with the 74 series 373
- ESD performance:
 - Human-body model > 2000V
 - Machine model > 200V
 - Charged-device model > 1000V

General Description

The LVT373 and LVTH373 consist of eight latches with 3-STATE outputs for bus organized system applications. The latches appear transparent to the data when Latch Enable (LE) is HIGH. When LE is LOW, the data satisfying the input timing requirements is latched. Data appears on the bus when the Output Enable (\overline{OE}) is LOW. When \overline{OE} is HIGH, the bus output is in a high impedance state.

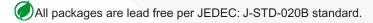
The LVTH373 data inputs include bushold, eliminating the need for external pull-up resistors to hold unused inputs.

These octal latches are designed for low-voltage (3.3V) V_{CC} applications, but with the capability to provide a TTL interface to a 5V environment. The LVT373 and LVTH373 are fabricated with an advanced BiCMOS technology to achieve high speed operation similar to 5V ABT while maintaining low power dissipation.

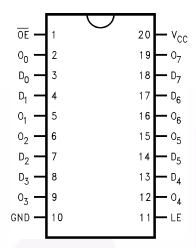
Ordering Information

| Order Number | Package Number | Package Description |
|--------------|-------------------|---|
| 74LVT373WM | M20B | 20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide |
| 74LVT373SJ | M20D | 20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide |
| 74LVT373MTC | MTC20 | 20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide |
| 74LVTH373WM | M20B | 20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide |
| 74LVTH373SJ | M20D | 20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide |
| 74LVTH373MTC | MTC20 | 20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide |

Device also available in Tape and Reel. Specify by appending suffix letter "X" to the ordering number.



Connection Diagram



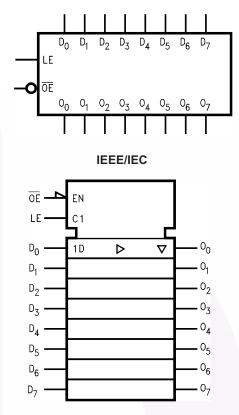
Pin Description

| Pin Names | Description |
|--------------------------------|-----------------------|
| D ₀ –D ₇ | Data Inputs |
| LE | Latch Enable Input |
| ŌĒ | Output Enable Input |
| O ₀ -O ₇ | 3-STATE Latch Outputs |

Functional Description

The LVT373 and LVTH373 contain eight D-type latches with 3-STATE standard outputs. When the Latch Enable (LE) input is HIGH, data on the D_n inputs enters the latches. In this condition the latches are transparent, i.e., a latch output will change state each time its D input changes. When LE is LOW, the latches store the information that was present on the D inputs a setup time preceding the HIGH-to-LOW transition of LE. The 3-STATE standard outputs are controlled by the Output Enable (\overline{OE}) input. When \overline{OE} is LOW, the standard outputs are in the 2-state mode. When \overline{OE} is HIGH, the standard outputs are in the high impedance mode but this does not interfere with entering new data into the latches.

Logic Symbols



Truth Table

| | Inputs | Outputs | |
|----|--------|----------------|----------------|
| LE | ŌĒ | D _n | O _n |
| Х | Н | Х | Z |
| Н | L | L | L |
| Н | L | Н | Н |
| L | L | Х | O ₀ |

H = HIGH Voltage Level

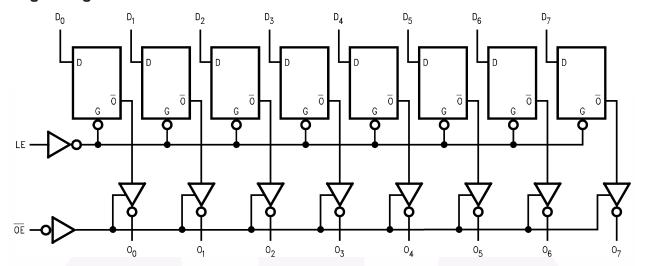
L = LOW Voltage Level

Z = High Impedance

X = Immaterial

 O_0 = Previous O_0 before HIGH-to-LOW transition of Latch Enable

Logic Diagram



Please note that this diagram is provided only for the understanding of logic operations and should not be used to estimate propagation delays.

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

| Symbol | Parameter | Rating | | |
|------------------|---|-----------------|--|--|
| V _{CC} | Supply Voltage | -0.5V to +4.6V | | |
| V _I | DC Input Voltage | -0.5V to +7.0V | | |
| Vo | DC Output Voltage | | | |
| | Output in 3-STATE | -0.5V to +7.0V | | |
| | Output in HIGH or LOW State ⁽¹⁾ | -0.5V to +7.0V | | |
| I _{IK} | DC Input Diode Current, V _I < GND | | | |
| I _{OK} | DC Output Diode Current, V _O < GND | | | |
| Io | DC Output Current, V _O > V _{CC} | | | |
| | Output at HIGH State | 64mA | | |
| | Output at LOW State | 128mA | | |
| I _{CC} | DC Supply Current per Supply Pin | ±64mA | | |
| I _{GND} | DC Ground Current per Ground Pin ±12 | | | |
| T _{STG} | Storage Temperature | −65°C to +150°C | | |

Note:

1. IO Absolute Maximum Rating must be observed.

Recommended Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to absolute maximum ratings.

| Symbol | Parameter | Min | Max | Units |
|-----------------|--|-----|-----|-------|
| V _{CC} | Supply Voltage | 2.7 | 3.6 | V |
| VI | Input Voltage | 0 | 5.5 | V |
| I _{OH} | HIGH-Level Output Current | | -32 | mA |
| I _{OL} | LOW-Level Output Current | | 64 | mA |
| T _A | Free-Air Operating Temperature | | 85 | °C |
| Δt / ΔV | Input Edge Rate, V _{IN} = 0.8V–2.0V, V _{CC} = 3.0V | 0 | 10 | ns/V |

DC Electrical Characteristics

| | | | | | T A = | 40°C to + | 85°C | | |
|-------------------------------------|---|--------------|---------------------|---|----------------------|---------------------|------|-------|--|
| Symbol | Parameter | | V _{CC} (V) | Conditions | Min. | Typ. ⁽²⁾ | Max. | Units | |
| V _{IK} | Input Clamp Di | ode Voltage | 2.7 | $I_I = -18mA$ | | | -1.2 | V | |
| V _{IH} | Input HIGH Vol | tage | 2.7–3.6 | $V_0 \le 0.1V$ or | 2.0 | | | V | |
| V _{IL} | Input LOW Voltage | | 2.7–3.6 | $V_O \ge V_{CC} - 0.1V$ | | | 0.8 | V | |
| V _{OH} | Output HIGH V | oltage/ | 2.7–3.6 | $I_{OH} = -100 \mu A$ | V _{CC} -0.2 | | | V | |
| | | | 2.7 | $I_{OH} = -8mA$ | 2.4 | | | | |
| | | | 3.0 | $I_{OH} = -32 \text{mA}$ | 2.0 | | | | |
| V _{OL} | Output LOW Vo | oltage | 2.7 | $I_{OL} = 100 \mu A$ | | | 0.2 | V | |
| | | | | I _{OL} = 24mA | | | 0.5 | | |
| | | | 3.0 | I _{OL} = 16mA | | | 0.4 | | |
| | | | | $I_{OL} = 32mA$ | | | 0.5 | | |
| | | | | I _{OL} = 64mA | | | 0.55 | | |
| I _{I(HOLD)} ⁽³⁾ | Bushold Input I | Minimum | 3.0 | V _I = 0.8V | 75 | | | μA | |
| | Drive | | | V _I = 2.0V | -75 | | | | |
| I _{I(OD)} (3) | Bushold Input | | 3.0 | (4) | 500 | | | μA | |
| Current to Cha | nge State | | (5) | -500 | | | 1 | | |
| I _I | I _I Input Current | | 3.6 | V _I = 5.5V | | | 10 | μА | |
| | | Control Pins | 3.6 | $V_I = 0V \text{ or } V_{CC}$ | | | ±1 | | |
| | | Data Pins | 3.6 | $V_I = 0V$ | | | -5 | | |
| | | | $V_I = V_{CC}$ | | | 1 | | | |
| I _{OFF} | Power Off Leal | kage Current | 0 | $0V \le V_I \text{ or } V_O \le 5.5V$ | | | ±100 | μA | |
| I _{PU/PD} | Power up/down 3-STATE Output Current | | 0–1.5V | $V_O = 0.5V \text{ to } 3.0V,$ $V_I = \text{GND or } V_{CC}$ | | | ±100 | μA | |
| I _{OZL} | 3-STATE Outpu Current | ut Leakage | 3.6 | $V_O = 0.5V$ | | | -5 | μA | |
| I _{OZH} | 3-STATE Output Current | ut Leakage | 3.6 | V _O = 3.0V | | | 5 | μА | |
| I _{OZH} + | 3-STATE Output Current | ut Leakage | 3.6 | $V_{CC} < V_O \le 5.5V$ | | | 10 | μA | |
| I _{CCH} | Power Supply Current | | 3.6 | Outputs HIGH | | | 0.19 | mA | |
| I _{CCL} | Power Supply Current | | 3.6 | Outputs LOW | | | 5 | mA | |
| I _{CCZ} | Power Supply Current | | 3.6 | Outputs Disabled | | | 0.19 | mA | |
| I _{CCZ} + | Power Supply Current | | 3.6 | $V_{CC} \le V_O \le 5.5V$, Outputs Disabled | | | 0.19 | mA | |
| Δl _{CC} | Increase in Power Supply Current ⁽⁶⁾ | | 3.6 | One Input at V _{CC} – 0.6V, Other Inputs at V _{CC} or GND | | | 0.2 | mA | |

Notes:

- 2. All typical values are at $V_{CC} = 3.3V$, $T_A = 25^{\circ}C$.
- 3. Applies to bushold versions only (74LVTH373).
- 4. An external driver must source at least the specified current to switch from LOW-to-HIGH.
- 5. An external driver must sink at least the specified current to switch from HIGH-to-LOW.
- 6. This is the increase in supply current for each input that is at the specified voltage level rather than V_{CC} or GND.

Dynamic Switching Characteristics⁽⁷⁾

| | | | Conditions | | $T_A = 25^{\circ}C$ | | |
|------------------|---|---------------------|---------------------------------|------|---------------------|------|-------|
| Symbol | Parameter | V _{CC} (V) | $C_L = 50 pF, R_L = 500 \Omega$ | Min. | Тур. | Max. | Units |
| V _{OLP} | Quiet Output Maximum Dynamic V _{OL} | 3.3 | (8) | | 0.8 | | V |
| V _{OLV} | Quiet Output Minimum Dynamic V _{OL} | 3.3 | (8) | | -0.8 | | V |

Notes:

- 7. Characterized in SOIC package. Guaranteed parameter, but not tested.
- 8. Max number of outputs defined as (n). n-1 data inputs are driven 0V to 3V. Output under test held LOW.

AC Electrical Characteristics

| | | | $T_A = -40$ °C to +85°C, $C_L = 50$ pF, $R_L = 500$ Ω | | | | |
|------------------|----------------------------------|----------------|---|------|-------------------|--------|-------|
| | | V _C | $_{\rm C} = 3.3 \rm V \pm 0$ |).3V | V _{CC} = | = 2.7V | |
| Symbol | Parameter | Min. | Typ. ⁽⁹⁾ | Max. | Min. | Max. | Units |
| t _{PHL} | Propagation Delay, | 1.5 | | 4.5 | 1.5 | 5.0 | ns |
| t _{PLH} | D_n to O_n | 1.5 | | 4.5 | 1.5 | 4.9 | |
| t _{PHL} | Propagation Delay, | 1.7 | | 4.6 | 1.7 | 4.9 | ns |
| t _{PLH} | LE to O _n | 1.7 | | 4.5 | 1.7 | 5.0 | |
| t _{PZL} | Output Enable Time | 1.3 | | 4.8 | 1.3 | 5.9 | ns |
| t _{PZH} | | 1.3 | | 4.8 | 1.3 | 5.5 | |
| t _{PLZ} | Output Disable Time | 1.9 | | 4.6 | 1.9 | 4.9 | ns |
| t _{PHZ} | | 1.9 | | 4.6 | 1.9 | 4.9 | |
| t _W | LE Pulse Width | 3.0 | | | 3.0 | | ns |
| t _S | Setup Time, D _n to LE | 1.1 | | | 1.0 | | ns |
| t _H | Hold Time, D _n to LE | 1.4 | | | 1.4 | | ns |

Note:

9. All typical values are at $V_{CC} = 3.3V$, $T_A = 25$ °C.

Capacitance⁽¹⁰⁾

| Symbol | Parameter | Parameter Conditions | | Units |
|------------------|--------------------|--|---|-------|
| C _{IN} | Input Capacitance | $V_{CC} = OPEN, V_I = 0V \text{ or } V_{CC}$ | 3 | pF |
| C _{OUT} | Output Capacitance | $V_{CC} = 3.0V$, $V_{O} = 0V$ or V_{CC} | 5 | pF |

Note:

10. Capacitance is measured at frequency f = 1MHz, per MIL-STD-883, Method 3012.

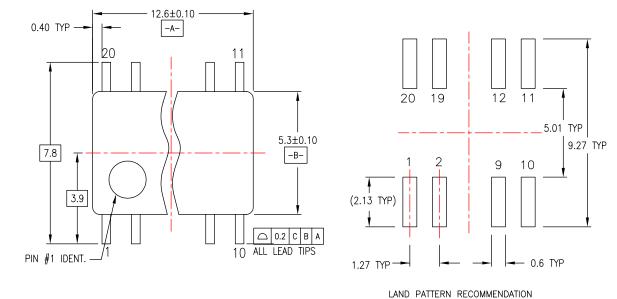
Physical Dimensions 13.00 12.60 11.43 В 9.50 10.65 7.60 10.00 7.40 PIN ONE 0.35 INDICATOR **⊕** 0.25 **M** C B A LAND PATTERN RECOMMENDATION 2.65 MAX SEE DETAIL A 0.33 0.20 △ 0.10 C 0.30 0.10 0.75 SEATING PLANE NOTES: UNLESS OTHERWISE SPECIFIED (R0.10) A) THIS PACKAGE CONFORMS TO JEDEC GAGE PLANE MS-013, VARIATION AC, ISSUE E (R0.10) B) ALL DIMENSIONS ARE IN MILLIMETERS. 0.25 C) DIMENSIONS DO NOT INCLUDE MOLD FLASH OR BURRS. D) CONFORMS TO ASME Y14.5M-1994 0.40 SEATING PLANE E) LANDPATTERN STANDARD: SOIC127P1030X265-20L (1.40)DETAIL A F) DRAWING FILENAME: MKT-M20BREV3

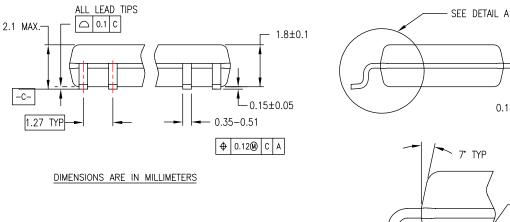
Figure 1. 20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide

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Physical Dimensions (Continued)

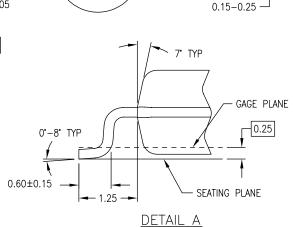




NOTES:

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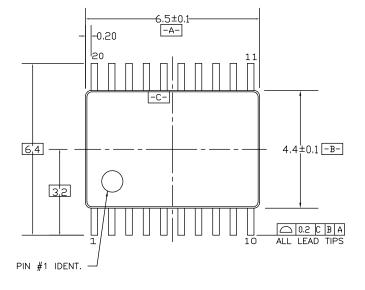
M20DREVC

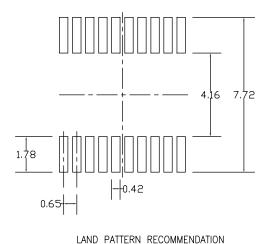
Figure 2. 20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide

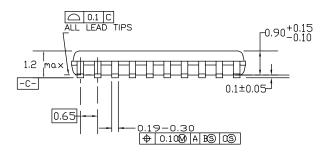
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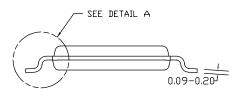


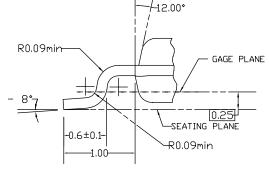


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- D. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M, 1982.





DETAIL A

MTC20REVD1

Figure 3. 20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide

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